# 3.3 V ECL 1:4 ÷1/÷2 Clock Fanout Buffer

# Description

The MC100LVEL37 is a fully differential 1:4 fanout buffer. The device offers two outputs at  $\div 1$  of the input frequency, and two outputs at  $\div 2$  of the input frequency. The Low Output-Output Skew of the device makes it ideal for distributing 1x and 1/2x frequency synchronous signals.

The differential inputs have special circuitry which ensures device stability under open input conditions. When both differential inputs are left open the CLKn input will pull down to  $V_{EE}$ , The  $\overline{CLKn}$  input will bias around  $V_{CC}/2$  and the Qn output will go LOW.

#### **Features**

- 700 ps Typical Propagation Delays
- 50 ps Maximum Output-Output Skews
- ESD Protection:
  - ♦ > 2 kV Human Body Model
  - ♦ > 200 V Machine Model
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: V<sub>CC</sub> = 3.0 V to 3.8 V with V<sub>EE</sub> = 0 V
- NECL Mode Operating Range: V<sub>CC</sub> = 0 V with V<sub>EE</sub> = -3.0 V to -3.8 V
- Internal Input Pulldown Resistors
- Qn Output will Default LOW with Inputs Open or at V<sub>EE</sub>
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity: Level 3 (Pb-Free)
   (For Additional Information, see Application Note <u>AND8003/D</u>)
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index 28 to 34
- Transistor Count = 256 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

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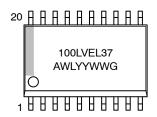
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SOIC-20 WB DW SUFFIX CASE 751D-05

# **MARKING DIAGRAM\***



A = Assembly Location

WL = Wafer Lot
 YY = Year
 WW = Work Week
 G = Pb-Free Package

\*For additional marking information, refer to Application Note <u>AND8002/D</u>.

## **ORDERING INFORMATION**

Device	Package	Shipping†
MC100LVEL37DWG	SOIC-20 WB (Pb-Free)	38 Units / Tube
MC100LVEL37DWR2G	SOIC-20 WB (Pb-Free)	1000Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

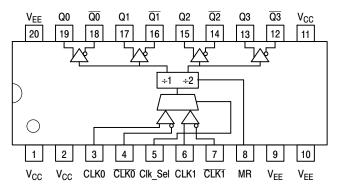


Figure 1. 20-Lead Pinout (Top View)

Warning: All  $V_{CC}$  and  $V_{EE}$  pins must be externally connected to Power Supply to guarantee proper operation.

**Table 1. TRUTH TABLE** 

Clk_Sel	MR	Q0, 1	Q2, 3
L	LLI	CLK0/÷1	CLK0/÷2
H		CLK1/÷1	CLK1/÷2
X		L	L

X = Don't Care

**Table 2. PIN DESCRIPTION** 

PIN	FUNCTION
Q0, Q0; Q1, Q1 Q2, Q2; Q3, Q3 CLKn, CLKn Clk_Sel MR V <sub>CC</sub> V <sub>EE</sub>	ECL Differential Clock ÷1 Outputs ECL Differential Clock ÷2 Outputs ECL Differential Clock Inputs ECL Input Clock Selection ECL Asynchronous Master Reset Positive Supply Negative Supply

**Table 3. MAXIMUM RATINGS** 

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	PECL Mode Power Supply	V <sub>EE</sub> = 0 V		8 to 0	V
V <sub>EE</sub>	NECL Mode Power Supply	V <sub>CC</sub> = 0 V		-8 to 0	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V <sub>EE</sub> = 0 V V <sub>CC</sub> = 0 V	$\begin{array}{c} V_I \leq V_{CC} \\ V_I \geq V_{EE} \end{array}$	6 to 0 -6 to 0	V
I <sub>out</sub>	Output Current	Continuous Surge		50 100	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction to Ambient)	0 lfpm 500 lfpm	SOIC-20 WB SOIC-20 WB	90 60	°C/W
θ <sub>JC</sub>	Thermal Resistance (Junction to Case)	Standard Board	SOIC-20 WB	30 to 35	°C/W
T <sub>sol</sub>	Wave Solder (Pb-Free)	< 2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. LVPECL DC CHARACTERISTICS (V<sub>CC</sub> = 3.3 V; V<sub>EE</sub> = 0.0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>EE</sub>	Power Supply Current		38	50		38	55		38	55	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V <sub>OL</sub>	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	1490		1825	1490		1825	1490		1825	mV
V <sub>IHCMR</sub>	Input HIGH Voltage Common Mode Range (Differential) (Note 3) V <sub>PP</sub> < 500 mV V <sub>PP</sub> ≥ 500 mV	1.3 1.5		2.9 2.9	1.2 1.4		2.9 2.9	1.2 1.4		2.9 2.9	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current CLKn CLKn	0.5 -300			0.5 –300			0.5 –300			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- Input and output parameters vary 1:1 with V<sub>CC</sub>. V<sub>EE</sub> can vary ±0.3 V.
   Outputs are terminated through a 50 Ω resistor to V<sub>CC</sub> 2.0 V.
   V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V<sub>PP</sub>min and 1 V.

Table 5. LVNECL DC CHARACTERISTICS ( $V_{CC} = 0.0 \text{ V}$ ;  $V_{EE} = -3.3 \text{ V}$  (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>EE</sub>	Power Supply Current		38	50		38	55		38	55	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 2)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V <sub>OL</sub>	Output LOW Voltage (Note 2)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	-1810		-1475	-1810		-1475	-1810		-1475	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential) (Note 3) V <sub>PP</sub> < 500 mV V <sub>PP</sub> ≥ 500 mV	-2.0 -1.8		-0.4 -0.4	-2.1 -1.9		-0.4 -0.4	-2.1 -1.9		-0.4 -0.4	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current CLKn CLKn	0.5 –300			0.5 –300			0.5 –300			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary  $\pm 0.3$  V.
- 2. Outputs are terminated through a 50  $\Omega$  resistor to  $V_{CC}$  2.0 V.
- 3. V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V<sub>PP</sub>min and 1 V.

Table 6. AC CHARACTERISTICS ( $V_{CC} = 3.3 \text{ V}$ ;  $V_{EE} = 0.0 \text{ V}$  or  $V_{CC} = 0.0 \text{ V}$ ;  $V_{EE} = -3.3 \text{ V}$  (Note 1))

			-40°C		25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
fmax	Maximum Toggle Frequency		TBD			TBD			TBD		GHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay CLK to Q/Q (Diff) CLK to Q/Q MR to Q	640 620 640		940 920 920	680 680 680	700 700 700	920 940 920	720 720 720		980 970 980	ps
t <sub>SKEW</sub>	Within-Device Skew (Note 2) Duty Cycle Skew (Differential Configuration) (Note 3)			50 50			50 50			50 50	ps
t <sub>JITTER</sub>	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
$V_{PP}$	Input Swing (Note 4)	150		1000	150		1000	150		1000	mV
t <sub>r</sub> t <sub>f</sub>	Output Rise/Fall Times Q (20%-80%)	280		550	280		550	280		550	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- V<sub>EE</sub> can vary ±0.3 V.
   Within-device skew defined as identical transitions on similar paths through a device.
- 3. Duty cycle skew is the difference between a TPLH and TPHL propagation delay through a device.
- 4. V<sub>PP</sub>(min) is minimum input swing for which AC parameters guaranteed. The device has a DC gain of ≈40.

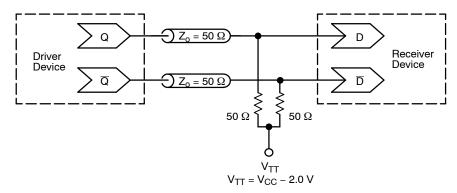


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note <u>AND8020/D</u> – Termination of ECL Logic Devices)

# **Resource Reference of Application Notes**

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AND8001/D - The ECL Translator Guide
AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

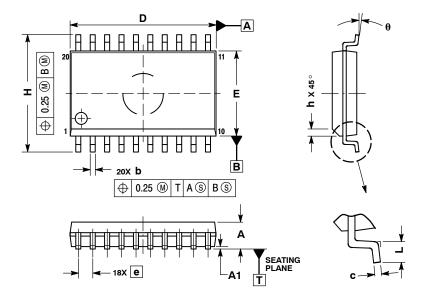
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

# **PACKAGE DIMENSIONS**

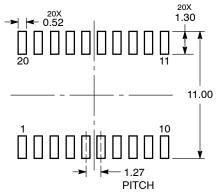
# SOIC-20 WB **DW SUFFIX** CASE 751D-05 **ISSUE H**



- NOTES:
  1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
  5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION, ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS							
DIM	MIN	MAX						
Α	2.35	2.65						
A1	0.10	0.25						
b	0.35	0.49						
C	0.23	0.32						
D	12.65	12.95						
E	7.40	7.60						
е	1.27	BSC						
Н	10.05	10.55						
h	0.25	0.75						
L	0.50	0.90						
θ	0 °	7 °						

# **RECOMMENDED SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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